

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT																
NATURE OF CONVEYANCE:	ASSIGNMENT																
CONVEYING PARTY DATA																	
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Chun-Ming Huang</td> <td>03/18/2010</td> </tr> <tr> <td>Chin-Long Wey</td> <td>03/18/2010</td> </tr> <tr> <td>Chien-Ming Wu</td> <td>03/18/2010</td> </tr> <tr> <td>Chih-Chyau Yang</td> <td>03/18/2010</td> </tr> <tr> <td>Shih-Lun Chen</td> <td>03/18/2010</td> </tr> <tr> <td>Chi-Shi Chen</td> <td>03/18/2010</td> </tr> <tr> <td>Chi-Sheng Lin</td> <td>03/18/2010</td> </tr> </tbody> </table>		Name	Execution Date	Chun-Ming Huang	03/18/2010	Chin-Long Wey	03/18/2010	Chien-Ming Wu	03/18/2010	Chih-Chyau Yang	03/18/2010	Shih-Lun Chen	03/18/2010	Chi-Shi Chen	03/18/2010	Chi-Sheng Lin	03/18/2010
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RECEIVING PARTY DATA																	
Name:	National Chip Implementation Center National Applied Research Laboratories																
Street Address:	7F. No. 26, Prosperity Rd. 1, Science Park																
City:	Hsinchu City																
State/Country:	TAIWAN																
Postal Code:	300																
PROPERTY NUMBERS Total: 1																	
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>12752345</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	12752345												
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Application Number:	12752345																
CORRESPONDENCE DATA																	
Fax Number:	(703)739-9557																
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PATENT
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NAME OF SUBMITTER:

Juan Carlos a. Marquez

Total Attachments: 2

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ASSIGNMENT


WHEREAS, **1. HUANG, Chun-Ming 2. WEY, Chin-Long 3. WU, Chien-Ming 4. YANG, Chih-Chyau 5. CHEN, Shih-Lun 6. CHEN, Chi-Shi 7. LIN, Chi-Sheng** whose post office addresses appear below hereinafter referred to as ASSIGNOR), have invented certain new and useful improvements in a **THREE-DIMENSIONAL SOC STRUCTURE FORMED BY STACKING MULTIPLE CHIP MODULES.** (hereinafter referred to as THE INVENTION) for which an application for United States Letters Patent was filed on _____, Application Number _____;


WHEREAS, **NATIONAL CHIP IMPLEMENTATION CENTER NATIONAL APPLIED RESEARCH LABORATORIES**, whose post office address is **7F, No. 26, Prosperity RD. 1, Science Park, Hsinchu City 300, Taiwan, R.O.C.** (hereinafter referred to as ASSIGNEE), is desirous of acquiring the entire right, title and interest in and to the same in the United States and throughout the world;

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, we, ASSIGNOR, by these presents do sell, assign and transfer until said ASSIGNEE, the entire right, title and interest in and to said invention and application throughout the United States of America, including any and all United States Letters Patent granted on any division, continuation, continuation-in-part and reissue of said application; and the entire right, title and interest in and to said invention throughout the world, including the right to apply for patents and inventor certificates in respect thereof and to claim priority pursuant to rights accorded ASSIGNOR under the terms of the Paris International Convention and all other available international conventions and treaties; and the entire right, title and interest in and to any and all patents, patents of addition, utility models, patents of importation, revalidation patents and inventor certificates which may be granted throughout the world in respect of said invention.

ALSO, ASSIGNOR hereby agrees to execute any documents that legally may be required in connection with the filing, prosecution and maintenance of said application or any other patent application(s) or inventor certificate(s) in the United States and in foreign countries for said invention, including additional documents that may be required to affirm the rights of ASSIGNEE in and to said invention, all without further consideration. ASSIGNOR also agrees, without further consideration and at ASSIGNEE'S expense, to identify and communicate to ASSIGNEE at ASSIGNEE'S request documents and information concerning the invention that are within ASSIGNOR'S possession or control, and to provide further assurances and testimony on behalf of ASSIGNEE that lawfully may be required of ASSIGNOR in respect of the prosecution, maintenance and defense of any patent application or patent encompassed within the terms of this instrument. ASSIGNOR'S obligations under this instrument shall extend to ASSIGNOR'S heirs, executors, administrators and other legal representatives.

ASSIGNOR hereby authorizes and requests the Commissioner of Patents and Trademarks to issue any and all United States Letters Patent referred to above to ASSIGNEE of the entire right, title and interest in and to the same, for ASSIGNEE'S sole use and behalf; and for the use and behalf of ASSIGNEE'S legal representatives and successors, to the full end of the term for which such Letters Patent may be granted, as fully and entirely as the same would have been held by ASSIGNOR had this assignment and sale not been made.

Name	HUANG, Chun-Ming	Signature 
Address	7F, No. 26, Prosperity Rd. 1, Science Park, Hsinchu City 300, Taiwan, R.O.C.	Date March 18, 2010

Name	WEY, Chin-Long	Signature 
Address	7F, No. 26, Prosperity Rd. 1, Science Park, Hsinchu City 300, Taiwan, R.O.C.	Date March 18, 2010

Name	WU, Chien-Ming	Signature Wu, Chien-Ming
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Name	YANG, Chih-Chyau	Signature Yang, Chih-Chyau
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Name	CHEN, Shih-Lun	Signature Chen, Shih-Lun
Address	7F, No. 26, Prosperity Rd. 1, Science Park, Hsinchu City 300, Taiwan, R.O.C.	Date March 18, 2010

Name	CHEN, Chi-Shi	Signature Chen, Chi-Shi
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Name	LIN, Chi-Sheng	Signature Lin, Chi-Sheng
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